



Material Content Data Sheet



Sales Product Name		IPL65R230C7		Issued		25. January 2018		
MA#		MA001168238						
Package		PG-VSON-4-1		Weight*		187.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.621	1.93	1.93	19294	19294
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		68	
	non noble metal	zinc	7440-66-6	0.051	0.03		271	
	non noble metal	iron	7439-89-6	1.017	0.54		5420	
wire	non noble metal	copper	7440-50-8	41.300	22.01	22.59	220088	225847
	non noble metal	copper	7440-50-8	0.904	0.48	0.48	4818	4818
	encapsulation	organic material	carbon black	1333-86-4	0.220	0.12		1170
plastics	plastics	epoxy resin	-	11.308	6.03		60261	
	inorganic material	silicondioxide	60676-86-0	98.261	52.36	58.51	523628	585059
	leadfinish	non noble metal	tin	7440-31-5	2.397	1.28	1.28	12776
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1343	1343
solder	noble metal	silver	7440-22-4	0.081	0.04		433	
	non noble metal	tin	7440-31-5	0.065	0.03		347	
	non noble metal	lead	7439-92-1	3.107	1.66	1.73	16557	17337
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		40	
	non noble metal	zinc	7440-66-6	0.030	0.02		160	
	non noble metal	iron	7439-89-6	0.601	0.32		3205	
	non noble metal	copper	7440-50-8	24.418	13.01	13.35	130121	133526
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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